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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	29080
Number of Logic Elements/Cells	77000
Total RAM Bits	5001216
Number of I/O	129
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	301-TFBGA
Supplier Device Package	301-MBGA (11x11)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgxfc5f7m11c8n

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Contents

Cyclone	V Device Overview	. 3
Ke	ey Advantages of Cyclone V Devices	. 3
Su	ummary of Cyclone V Features	.4
	vclone V Device Variants and Packages	
•	Cyclone V E	
	Cyclone V GX	. 7
	Cyclone V GT	
	Cyclone V SE	
	Cyclone V SX	
	Cyclone V ST	
I/0	O Vertical Migration for Cyclone V Devices	
-	daptive Logic Module	
	riable-Precision DSP Block	
En	nbedded Memory Blocks	21
	Types of Embedded Memory	
	Embedded Memory Capacity in Cyclone V Devices	
	Embedded Memory Configurations	22
Cle	ock Networks and PLL Clock Sources	22
FP	PGA General Purpose I/O	23
PC	CIe Gen1 and Gen2 Hard IP	24
Ex	ternal Memory Interface	24
	Hard and Soft Memory Controllers	
	External Memory Performance	
	HPS External Memory Performance	
Lo	w-Power Serial Transceivers	
	Transceiver Channels	
	PMA Features	
	PCS Features	
Sc	oC with HPS	
	HPS Features	
	FPGA Configuration and Processor Booting	
	Hardware and Software Development	
Dy	namic and Partial Reconfiguration	
	Dynamic Reconfiguration	
	Partial Reconfiguration	
	hanced Configuration and Configuration via Protocol	
	wer Management	
Do	ocument Revision History for Cyclone V Device Overview	33



Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues

Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	 Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration



Summary of Cyclone V Features

Summary of Features for Cyclone V Devices Table 2.

Feature		Description				
Technology	TSMC's 28-nm low-p 1.1 V core voltage	, , , , , , , , , , , , , , , , , , , ,				
Packaging	 Wirebond low-halogen packages Multiple device densities with compatible package footprints for seamless migration between different device densities RoHS-compliant and leaded⁽¹⁾options 					
High-performance FPGA fabric	Enhanced 8-input ALM v	vith four registers				
Internal memory blocks	•	(b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory				
Embedded Hard IP blocks	Variable-precision DSP	 Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block 64-bit accumulator and cascade Embedded internal coefficient memory Preadder/subtractor for improved efficiency 				
	Memory controller DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support					
	Embedded transceiver I/O PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port					
Clock networks		ol clock network d peripheral clock networks are not used can be powered down to reduce dynamic power				
Phase-locked loops (PLLs)	Precision clock synthInteger mode and from	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode				
FPGA General-purpose I/Os (GPIOs)	 875 megabits per second (Mbps) LVDS receiver and 840 Mbps LVDS transmitter 400 MHz/800 Mbps external memory interface On-chip termination (OCT) 3.3 V support with up to 16 mA drive strength 					
Low-power high-speed serial interface	 614 Mbps to 6.144 Gbps integrated transceiver speed Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels 					
HPS (Cyclone V SE, SX, and ST devices only)	 Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I²C interface, and up to 85 HPS GPIO interfaces 					
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers ot ROM				
	·	continued				

⁽¹⁾ Contact Intel for availability.



Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight™ JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing (2) Partial reconfiguration (3)

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel® sales representatives.



Resource		Member Code						
		С3	C4	C5	С7	C9		
LVDS	Transmitter	52	84	84	120	140		
	Receiver	52	84	84	120	140		
PCIe Hard IP Block		1	2	2	2	2		
Hard Memory Controller		1	2	2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 7. Package Plan for Cyclone V GX Devices

Member Code	M3 (11)	801 mm)	M3 (13 i		M4 (15		U3 (15		U4 (19 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	_	_	_	_	_	_	144	3	208	3
C4	129	4	175	6	_	_	_	_	224	6
C5	129	4	175	6	_	_	_	_	224	6
C7	_	_	_	_	240	3	_	_	240	6
C9	_	_	_	_	_	_	_	_	240	5

Member Code	F4 (23 i		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
С3	208	3	_	_	_	_	_	_
C4	240	6	336	6	_	_	_	_
C5	240	6	336	6	_	_	_	_
C7	240	6	336	9	480	9	_	_
С9	224	6	336	9	480	12	560	12

Cyclone V GT

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

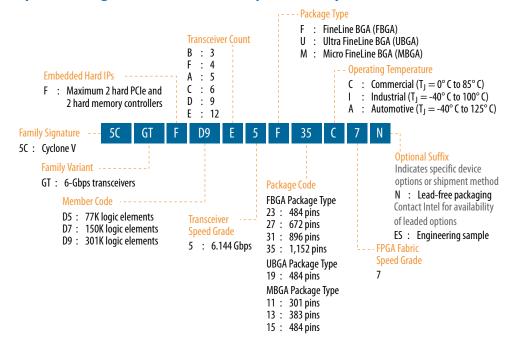
Product Selector Guide

Provides the latest information about Intel products.



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Re	Resource		Member Code					
		D5	D7	D9				
Logic Elements (LE) (K)		77	150	301				
ALM		29,080	56,480	113,560				
Register		116,320 225,920 454,2		454,240				
Memory (Kb)	M10K	4,460	6,860	12,200				
	MLAB	424	836	1,717				
Variable-precision DS	P Block	150	156	342				
18 x 18 Multiplier		300	312	684				
PLL		6	7	8				
6 Gbps Transceiver		6	9	12				
GPIO ⁽⁵⁾		336	480	560				
LVDS	Transmitter	84	120	140				
	,	•		continued				

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Resource		Member Code				
		D5 D7		D9		
Receiver		84	120	140		
PCIe Hard IP Block		2	2	2		
Hard Memory Controller		2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 9. Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver ≤ 5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code				M4 (15 i		U484 (19 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	_	_	224	6
D7	_	_	_	_	240	3	240	6
D9	_	_	_	_	_	_	240	5

Member Code	F48 (23 I			F672 F896 (27 mm) (31 mm)			F11 (35 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	240	6	336	6	_	_	_	_
D7	240	6	336	9 (6)	480	9 (6)	_	_
D9	224	6	336	9 (6)	480	12 ⁽⁷⁾	560	12 ⁽⁷⁾

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽⁶⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

⁽⁷⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Maximum Resources

Table 10. **Maximum Resource Counts for Cyclone V SE Devices**

Res	ource		Me	ember Code	
		A2	A4	A5	A6
Logic Elements (LE) (K)	25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precisio	n DSP Block	36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Package Plan for Cyclone V SE Devices Table 11.

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)		U672 (23 mm)		F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181



Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

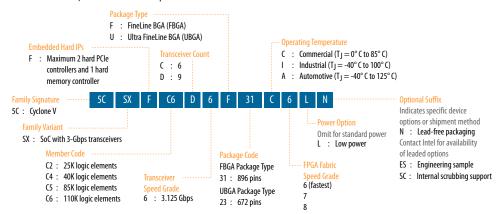
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Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Maximum Resources

Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resource		Member Code					
		C2	C4	C5	C6		
Logic Elements (LE) (K)		25	40	85	110		
ALM		9,430	15,880	32,070	41,910		
Register		37,736	60,376	128,300	166,036		
Memory (Kb)	M10K	1,400	2,700	3,970	5,570		
	MLAB	138	231	480	621		
Variable-precision [DSP Block	36	84	87	112		
18 x 18 Multiplier		72	168	174	224		
FPGA PLL		5	5	6	6		
					continued		



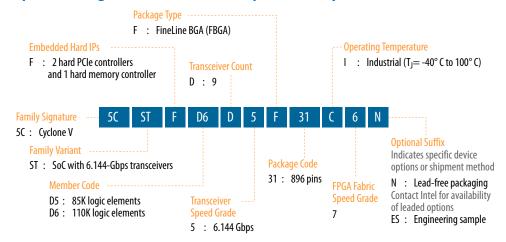
Related Information

Product Selector Guide

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Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Reso	ource	Membe	r Code
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO ⁽¹⁰⁾		288	288
HPS I/O		181	181
LVDS Transmitter		72	72
			continued

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Reso	urce	Member Code		
		D5	D6	
Receiver		72	72	
PCIe Hard IP Block		2	2	
FPGA Hard Memory Controller		1	1	
HPS Hard Memory Controller		1	1	
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the Cyclone V Device Handbook Volume 2: Transceivers.

Member Code	F896 (31 mm)						
	FPGA GPIO	HPS I/O	XCVR				
D5	288	181	9 (11)				
D6	288	181	9 (11)				

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

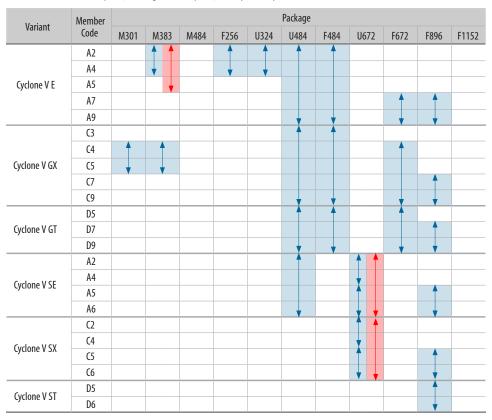
⁽¹¹⁾ If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note:

To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Table 16. Variable-Precision DSP Block Configurations for Cyclone V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters and general DSP usage	Two 18 x 18 with accumulate	1
High precision fixed- or floating-point implementations	One 27 x 27 with accumulate	1

You can configure each DSP block during compilation as independent three 9 \times 9, two 18 \times 18, or one 27 \times 27 multipliers. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 17. Number of Multipliers in Cyclone V Devices

The table lists the variable-precision DSP resources by bit precision for each Cyclone V device.

Variant	Member Code	Variable- precision DSP Block		Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Summed with 36 bit Input
Cyclone V E	A2	25	75	50	25	25	25
	A4	66	198	132	66	66	66
	A5	150	450	300	150	150	150
	A7	156	468	312	156	156	156
	A9	342	1,026	684	342	342	342
Cyclone V	C3	57	171	114	57	57	57
GX	C4	70	210	140	70	70	70
	C5	150	450	300	150	150	150
	C7	156	468	312	156	156	156
	C9	342	1,026	684	342	342	342
Cyclone V GT	D5	150	450	300	150	150	150
	D7	156	468	312	156	156	156
	D9	342	1,026	684	342	342	342
Cyclone V SE	A2	36	108	72	36	36	36
	A4	84	252	168	84	84	84
	A5	87	261	174	87	87	87
	A6	112	336	224	112	112	112
Cyclone V SX	C2	36	108	72	36	36	36
	C4	84	252	168	84	84	84
	C5	87	261	174	87	87	87
							continued



Variant	Member Code	Variable- precision DSP Block	Independent Input and Output Multiplications Operator		18 x 18 Multiplier	18 x 18 Multiplier		
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input	
	C6	112	336	224	112	112	112	
Cyclone V ST	D5	87	261	174	87	87	87	
	D6	112	336	224	112	112	112	

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Cyclone V Devices

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Member	M1	ОК	ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Fre	quency (MHz)	Minimum Frequency	
	(V)	Hard Controller	Soft Controller	(MHz)	
DDR3 SDRAM	1.5	400	303	303	
	1.35	400	303	303	
DDR2 SDRAM	1.8	400	300	167	
LPDDR2 SDRAM	1.2	333	300	167	

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic	Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	Custom PHY IP core with preset feature GbE transmitter synchronization state machine	Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core Dedicated XAUI PHY IP	
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding	Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	,		continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

⁽¹³⁾ XAUI is supported through the soft PCS.

 $^{^{(14)}}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.



PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	Custom PHY IP core with preset feature Electrical idle	Custom PHY IP core with preset feature Signal detect Wider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	Dedicated deterministic latency PHY IP core	Dedicated deterministic latency PHY IP core
OBSAI RP3	0.768 to 3.072	Transmitter (TX) manual bit-slip mode	Receiver (RX) deterministic latency state machine
V-by-One HS	Up to 3.75	Custom PHY IP core	Custom PHY IP core
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		Wider spread of asynchronous SSC

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support $1.8\ V$, $2.5\ V$, $3.0\ V$, and $3.3\ V$ programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Date	Version	Changes
		 Updated HPS I/O for U484 (19 mm) in Table 11 with '151' for A2, A4, A5 and A6. Updated Memory (Kb) for Maximum Resource Counts for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices. Updated FPGA PLL for Maximum Resource Counts for Cyclone V SE A2, SX C2, devices. Removed '36 x 36' from the Variable-Precision DSP Block. Updated Variable-precision DSP Blocks and 18 x 18 Multiplier for Maximum Resource Counts for Cyclone V SX C4 device. Updated the HPS I/O counts for Cyclone V SE, SX, and ST devices. Updated Figure 7 which shows the I/O vertical migration table. Updated Table 17 for Cyclone V SX C4 device. Updated Embedded Memory Capacity and Distribution table for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices. Removed 'Counter reconfiguration' from the PLL Features. Updated Low-Power Serial Transceivers by replacing 5 Gbps with 6.144 Gbps. Removed 'Distributed Memory' symbol. Updated the Capability in Table 22 of Backplane support to '6.144 Gbps'. Updated Capability in Table 22 of Ring oscillator transmit PLLs with 6.144 Gbps. Updated the PCS Support in Table 23 from 5 Gbps to '6 Gbps'. Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'. Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'. Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature.
December 2012	2012.12.28	 Updated the pin counts for the MBGA packages. Updated the GPIO and transceiver counts for the MBGA packages. Updated the GPIO counts for the U484 package of the Cyclone V E A9, GX C9, and GT D9 devices. Updated the vertical migration table for vertical migration of the U484 packages. Updated the MLAB supported programmable widths at 32 bits depth.
November 2012	2012.11.19	 Added new MBGA packages and additional U484 packages for Cyclone V E, GX, and GT. Added ordering code for five-transceiver devices for Cyclone V GT and ST. Updated the vertical migration table to add MBGA packages. Added performance information for HPS memory controller. Removed DDR3U support. Updated Cyclone V ST speed grade information. Added information on maximum transceiver channel usage restrictions for PCI Gen2 and CPRI at 4.9152 Gbps transmit jitter compliance. Added note on the differences between GPIO reported in Overview with User I/O numbers shown in the Quartus II software. Updated template.
July 2012	2.1	Added support for PCIe Gen2 x4 lane configuration (PCIe-compatible)
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 16, Table 19, and Table 20. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 12, Table 13, Table 14, Table 17, and Table 18.



Date	Version	Changes
		 Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.2	 Updated Table 1-2, Table 1-3, and Table 1-6. Updated "Cyclone V Family Plan" on page 1-4 and "Clock Networks and PLL Clock Sources" on page 1-15. Updated Figure 1-1 and Figure 1-6.
November 2011	1.1	 Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6. Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8. Updated "System Peripherals" on page 1-18, "HPS-FPGA AXI Bridges" on page 1-19, "HPS SDRAM Controller Subsystem" on page 1-19, "FPGA Configuration and Processor Booting" on page 1-19, and "Hardware and Software Development" on page 1-20. Minor text edits.
October 2011	1.0	Initial release.